Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN145326 **Date:** July 31, 2014

Subject: PCN 125156 Addendum 3: Qualification of Copper Wire Bonds for select Lead Frame (LF) Products

To: PCN ADMIN
CYPRESS
pcn_adm@cypress.com

Change Type: Major

Description of Change:
Cypress announced the qualification of copper wire bonds for lead frame products at Cypress Philippines, ASE Taiwan and OSE Taiwan using the Bill of Materials in the attached tables through PCN 125156. This PCN Addendum adds Specialty Memories parts assembled at ASE Taiwan that were not included in the original parts list. There are no changes to product datasheets.

Benefit of Change:
The conversion to copper wire bonds will keep Cypress in alignment with the overall industry trend towards copper wire bonds. This also provides the means for Cypress to continue to meet customers' varied packaging needs as well as delivery commitments in dynamic, changing market conditions.

Affected Part Numbers:
Affected Parts: 27
See the attached file for a list of part numbers affected by this change.

Qualification Status:
Copper wire bonds have been qualified through a series of tests documented in Qualification Test Plan (QTP) report number 120201. This qualification report can be found as an attachment to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:
Please contact your sales representative or the PCN Administrator as soon as possible to place any sample requests.

Approximate Implementation Date:
Cypress apologizes that this change has been implemented prematurely for some of the parts. Future shipments of the affected part numbers in the attached file may be with either copper wire bonds or gold wire bonds.

Anticipated Impact:
Products manufactured with copper wire bonds are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
There will be no changes to the part number. A "C" is added to the package marking to designate copper wire bonds. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required. Customers who do not wish to receive these parts with copper wires should request the creation of a custom part number restricted to gold wire bonds.

For additional information regarding this change, contact your sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration